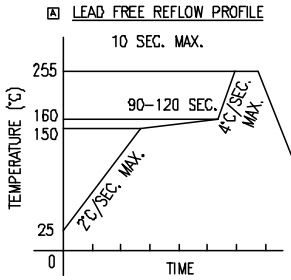
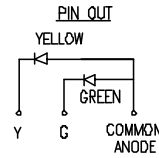
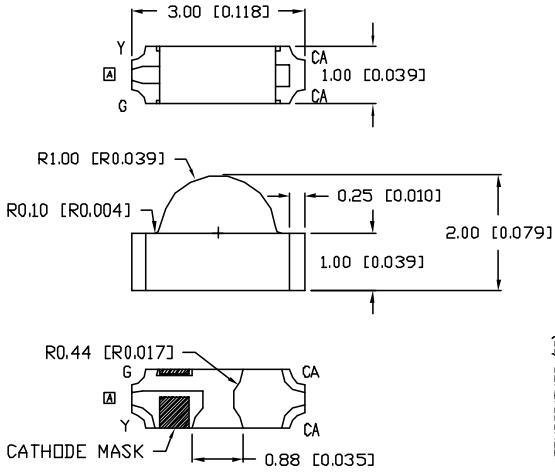


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PART NUMBER  
SML-LXR851SYSUGCTR

REV.  
A

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11494 & 1148.	04.08.08



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		590 (YELLOW)		nm	
		574 (GREEN)		nm	
FORWARD VOLTAGE (Y/G)		2.0/2.2	2.4/2.6	V <sub>f</sub>	
REVERSE VOLTAGE	5.0			V <sub>r</sub>	I <sub>f</sub> =100μA
AXIAL INTENSITY (Y/G)		50/20		mcd	I <sub>f</sub> =20mA
VIEWING ANGLE		120		2x theta	
EMITTED COLOR:	YELLOW/GREEN				
EPOXY LENS FINISH:	WATER CLEAR				

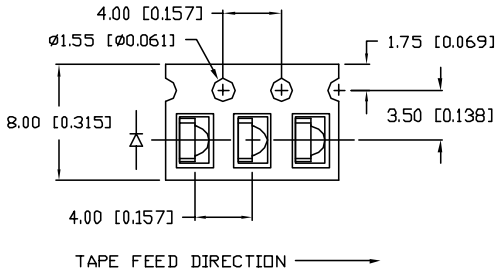
LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		160	mA
STEADY CURRENT (Y/G)		30/25	mA
POWER DISSIPATION		100	mW
DERATE FROM 25°C		-1.2	mW/°C
OPERATING TEMP.		-40 TO +85	°C
STORAGE TEMP.		-40 TO +85	°C

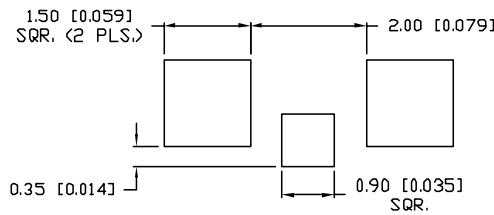
\*  $t < 10\mu\text{s}$

NOTES:

1. 2,000 PER REEL.



RECOMMENDED SOLDER PAD LAYOUT



CAUTION: MOISTURE SENSITIVE DEVICE  
PER JEDEC LEVEL 4 STANDARDS

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030). MIN= -0.00 DECIMAL PRECISION MAX.= +0.00 DECIMAL PRECISION

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REV.	PART NUMBER
A	SML-LXR851SYSUGCTR

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SURFACE MOUNT RIGHT ANGLE LED, BICOLOR,  
 590nm YELLOW/574nm GREEN, WATER CLEAR LENS.

RELIABILITY NOTE  
 OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JD	CHECKED BY:	APPROVED BY:	DATE: 9.16.04
			PAGE: 1 OF 1
			SCALE: N/A